#### **JOC827 Series**

### **DC Input, Phototransistor Photo Coupler**

#### **Description**

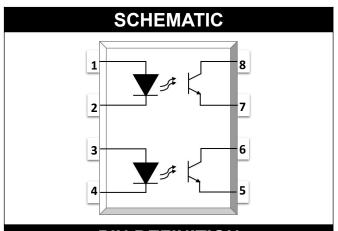
The JOC827 series provide two channel operation, and each combines an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic DIP8 package with different lead forming options. With the robust coplanar double mold structure, JOC827 series provide the most stable isolation feature.

#### **Features**

- High isolation 5000 VRMS
- DC input with transistor output
- Operating temperature range 55 °C to 110 °C
- REACH compliance
- Halogen free (Optional)
- MSL class 1
- Regulatory Approvals
  - UL
  - VDE
  - CQC

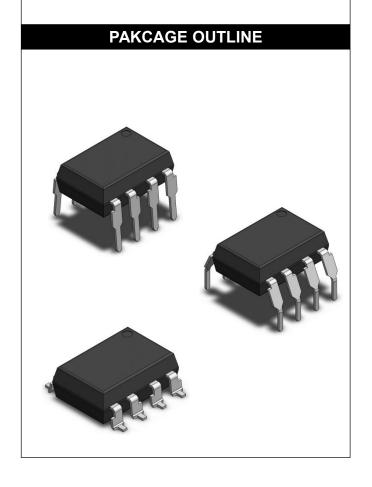
#### **Applications**

- Computer peripheral interface
- Microprocessor system interface



#### **PIN DEFINITION**

- 1. Anode
- 8. Collector
- 2. Cathode
- 7. Emitter
- 3. Anode
- 6. Collector
- 4. Cathode
- 5. Emitter



# JieJie Microelectronics CO., Ltd DC Input, Phototransistor Photo Coupler

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	VALUE	UNIT	NOTE			
INI	INPUT						
Forward Current	I <sub>F</sub>	60	mA				
Peak Forward Current	I <sub>FP</sub>	1	Α	1			
Reverse Voltage	V <sub>R</sub>	6	V				
Input Power Dissipation	Pı	100	mW				
OUTPUT							
Collector - Emitter Voltage	V <sub>CEO</sub>	80	V				
Emitter - Collector Voltage	V <sub>ECO</sub>	6	V				
Collector Current	Ic	50	mA				
Output Power Dissipation	Po	150	mW				
COMMON							
Total Power Dissipation	Ptot	200	mW				
Isolation Voltage	Viso	5000	Vrms	2			
Operating Temperature	Topr	-55~110	°C				
Storage Temperature	Tstg	-55~125	°C				
Soldering Temperature	Tsol	260	°C				

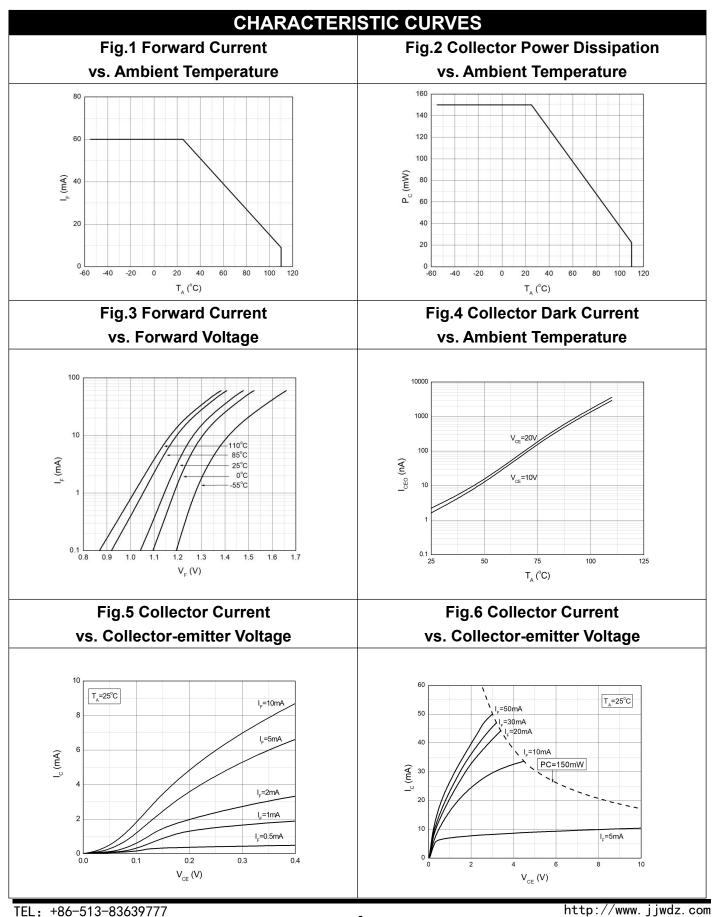
Note 1. 100µs pulse, 100Hz frequency

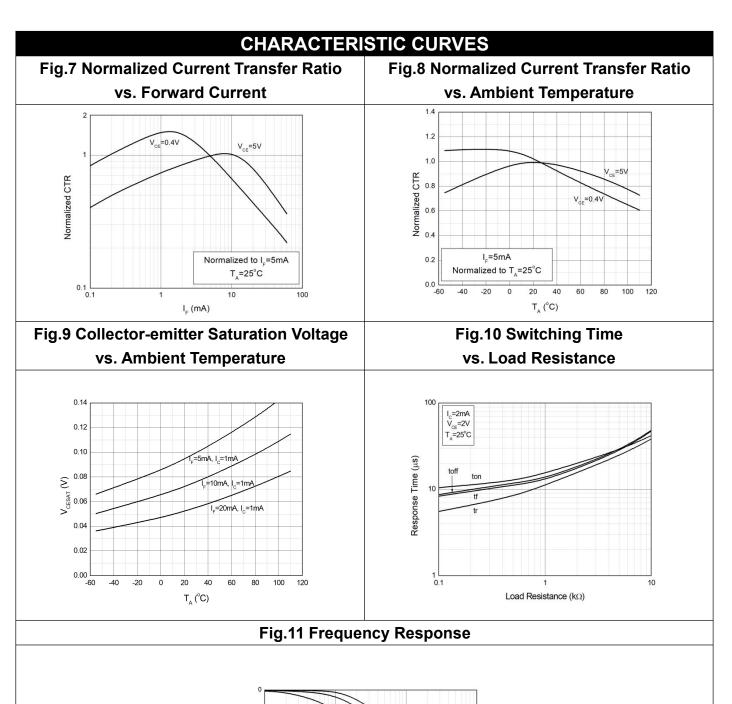
Note 2. AC For 1 Minute, R.H. =  $40 \sim 60\%$ 

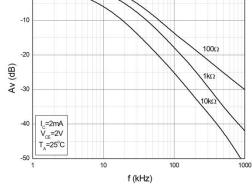
# JieJie Microelectronics CO., Ltd DC Input, Phototransistor Photo Coupler

	ELECT	RICAL OI	PTICA	L CHA	RAC	TER	ISTICS at Ta=25°C		
PARAME	TER	SYMBOL	MIN	TYP.	MAX.	UNIT	TEST CONDITION	NOTE	
	INPUT								
Forward V	oltage	V <sub>F</sub>	-	1.24	1.4	V	IF=10mA		
Reverse C	Current	I <sub>R</sub>	-	-	10	μA	VR=6V		
Input Capa	citance	Cin	-	10	-	pF	V=0, f=1kHz		
	OUTPUT							•	
Collector Dar	k Current	I <sub>CEO</sub>	-	-	100	nA	VCE=20V, IF=0		
Collector-E	Emitter	D\/	80			V	IC-0.1mA IF-0		
Breakdown	Voltage	BV <sub>CEO</sub>	80	-	-	V	IC=0.1mA, IF=0		
Emitter-Co	ollector	D\/	6			V	IE-0.1mA IE-0		
Breakdown	Voltage	BV <sub>ECO</sub>	0	-	-	V	IE=0.1mA, IF=0		
	TRANSFER CHARACTERISTICS								
Current									
Transfer	JOC827	CTR	130	-	400	%	IF=5mA, VCE=5V		
Ratio									
Collector-E	Emitter	\/	_	0.06	0.2	V	IF=20mA, IC=1mA		
Saturation \	Voltage	V <sub>CE(sat)</sub>	-	0.00	0.2	V	IF-20IIIA, IC-IIIIA		
Isolation Re	sistance	R <sub>ISO</sub>	10^12	10^14	-	Ω	DC500V, 40 ~ 60% R.H.		
Floating Cap	acitance	C <sub>IO</sub>	-	0.4	1	pF	V=0, f=1MHz		
Response Tir	ne (Rise)	tr	-	6	18	μs	VCE=2V, IC=2mA	3	
Response Ti	Response Time (Fall)		-	8	18	μs	RL=100Ω	3	
Cut-off Frequency		fo	-	80 -	- kHz	IzU=	VCE=2V, IC=2mA		
		fc				RL=100Ω,-3dB	4		

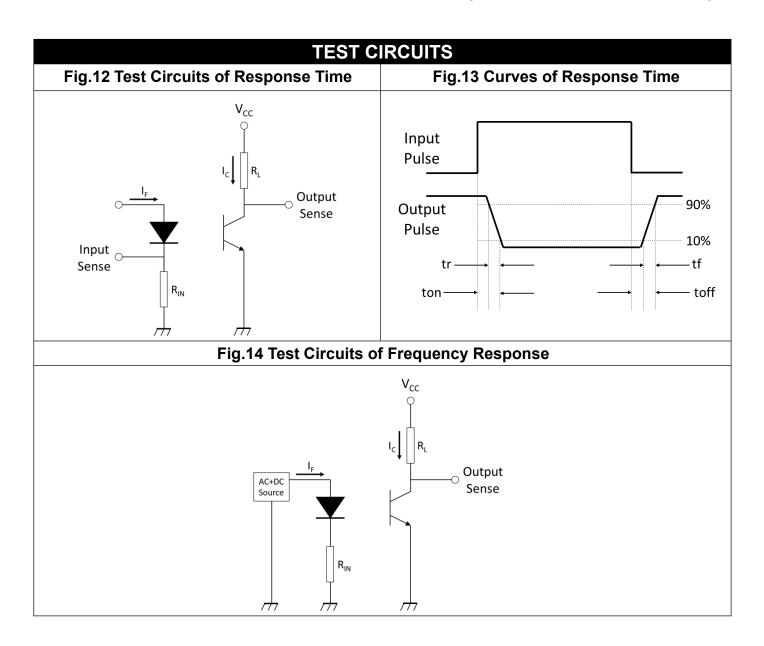
Note 3. Fig.14 Note 4. Fig.12&13





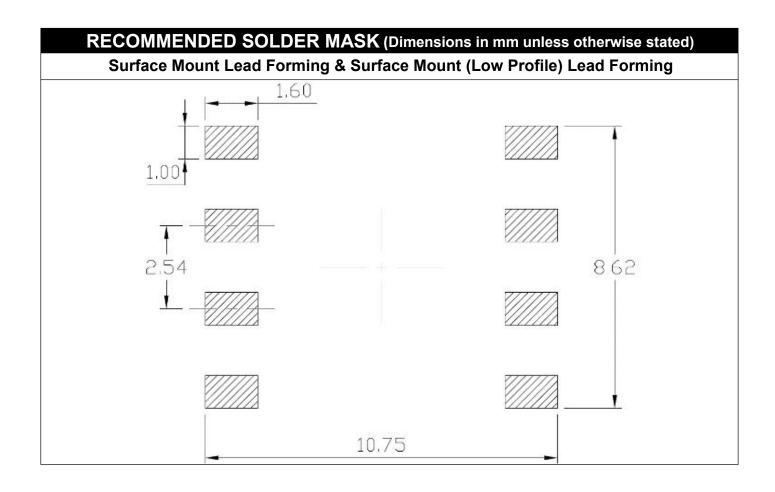


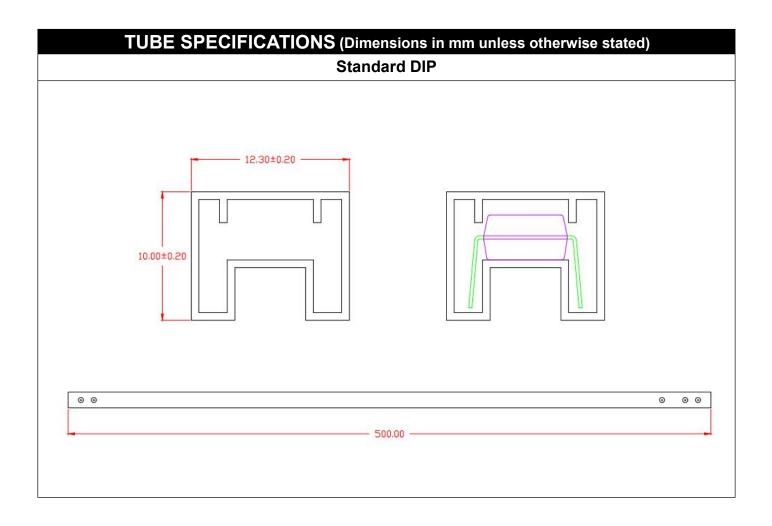
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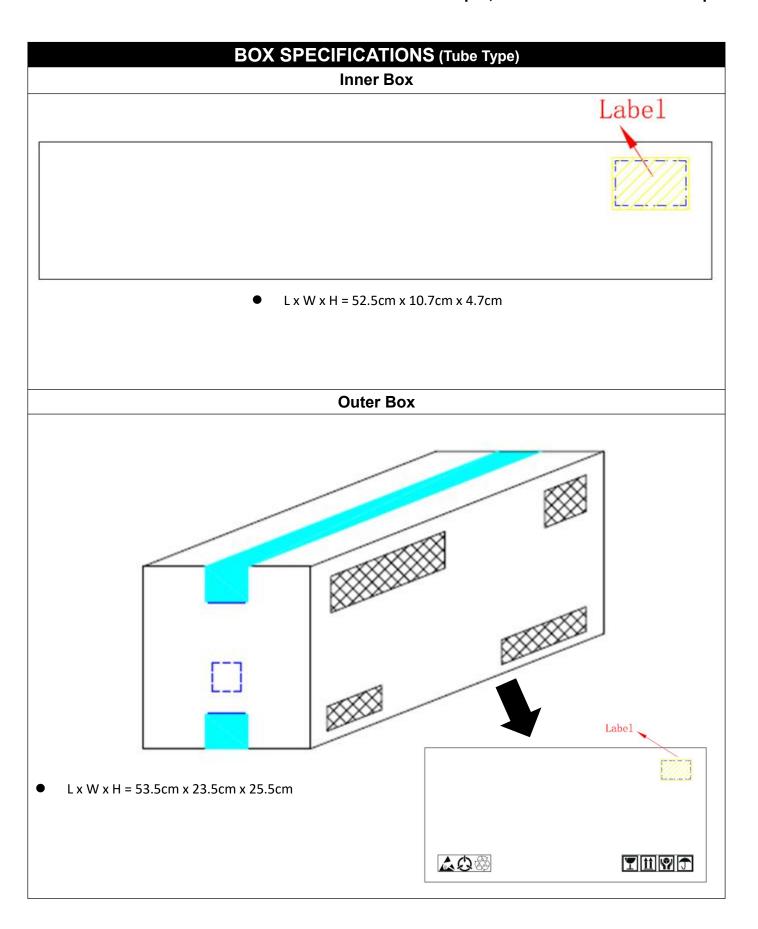


# PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated) Standard DIP - Through Hole (DIP Type) 6.60±0.20 9.76±0.20 7.62±0.30 1.30±0.10 3.50±0.20 4.50±0.30 Тур.2.80 Typ.0.25 5°~15° Typ.2.54 Typ.0.50 7.62~9.50 Gullwing (400mil) Lead Forming – Through Hole (M Type) 6.60±0.20 9.76±0.20 7.62±0.30 1.30±0.10 3.50±0.20 4.58±0.30 Typ.2.20 Typ.0.25 10.16±0.30 Typ.0.50 Typ.2.54

# PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated) **Surface Mount Lead Forming (S Type)** 6.60±0.20 9.76±0.20 7.62±0.30 1.30±0.10 3.50±0.20 | Typ.0.25 4.30±0.30 Typ.0.80 Typ.0.80 10.15±0.30 Тур.0.50 Typ.2.54 Surface Mount (Low Profile) Lead Forming (SL Type) 6.60±0.20 9.76±0.20 7.62±0.30 1.30±0.10 3.50±0.20 Typ.0.25 3.60±0.30 Тур.0.10 Typ.0.80 10.15±0.30 Typ.0.50 Typ.2.54

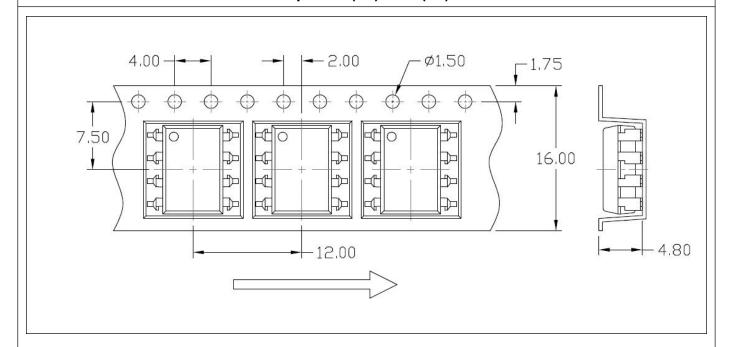




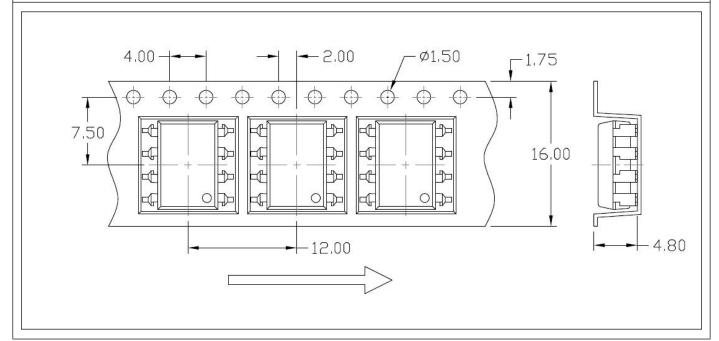


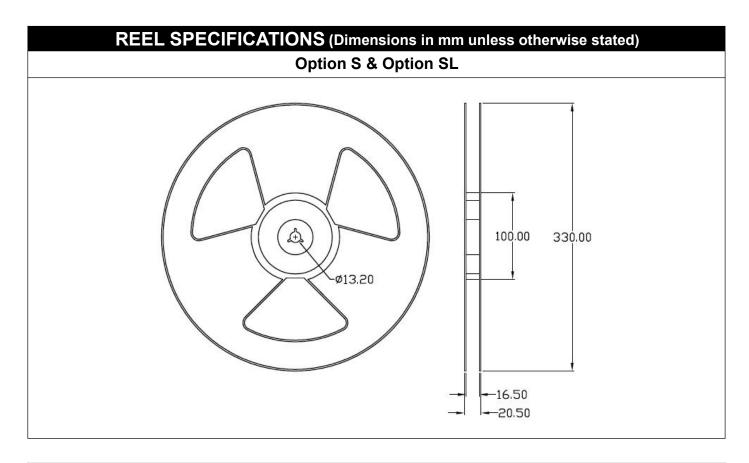
### Carrier Tape Specifications (Dimensions in mm unless otherwise stated)

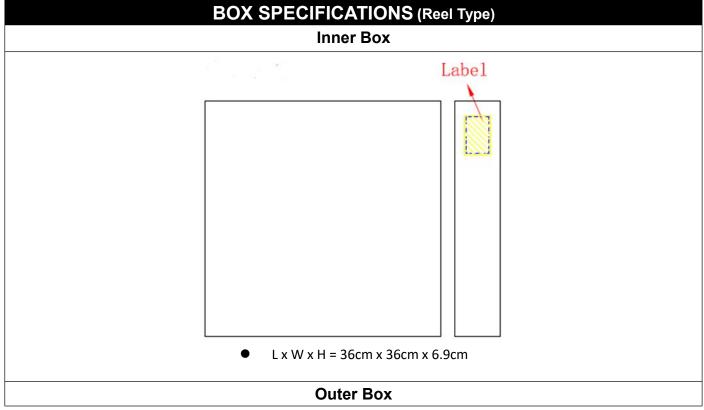
#### Option S(T1) & SL(T1)

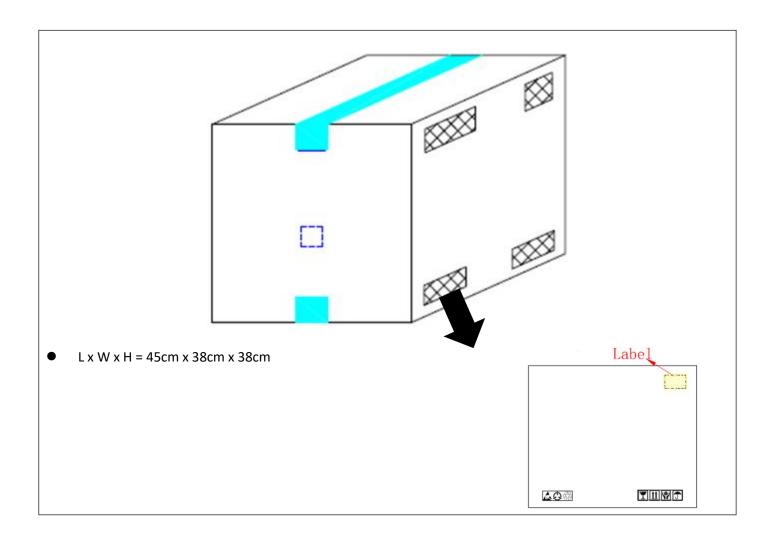


#### Option S(T2) & SL(T2)



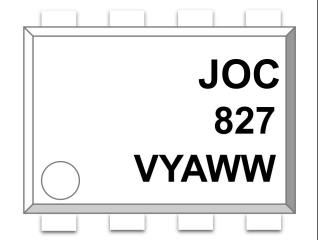






### **ORDERING AND MARKING INFORMATION**

#### MARKING INFORMATION



JOC : Company Abbr.

827 : Part Number

V : VDE Option

Y: Fiscal Year

A : Manufacturing Code

WW : Work Week

#### ORDERING INFORMATION

## JOC827(Y)(Z)-GV

JOC - Company Abbr.

827 - Part Number

Y – Lead Form Option (M/S/SL/None)

Z – Tape and Reel Option (T1/T2)

G – Material Option

(G: Green, None: Non-Green)

V – VDE Option (V or None)

#### **LABEL INFORMATION**

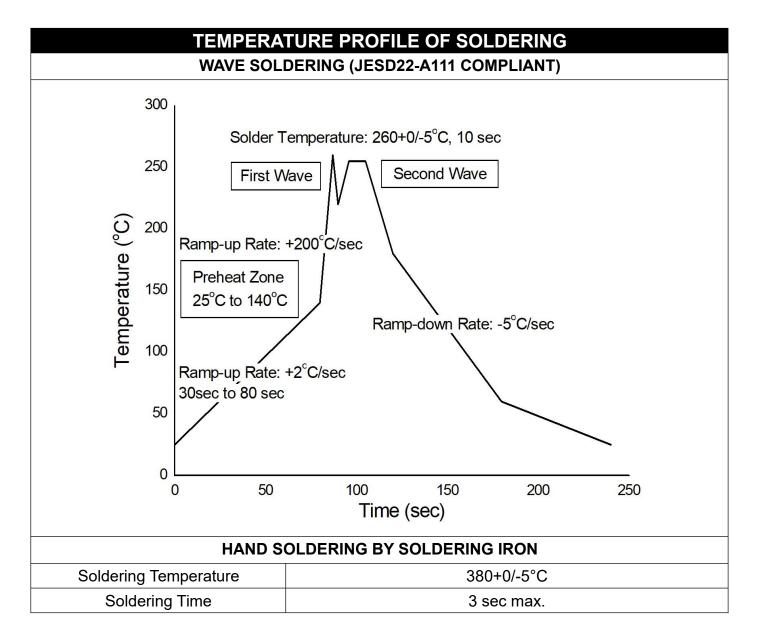


#### **PACKING QUANTITY**

Option	Quantity	Quantity – Inner box	Quantity – Outer box
None	40 Units/Tube	30 Tubes/Inner box	10 Inner box/Outer box = 12k Units
М	40 Units/Tube	30 Tubes/Inner box	10 Inner box/Outer box = 12k Units
S(T1)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
S(T2)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
SL(T1)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
SL(T2)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units

## **REFLOW INFORMATION REFLOW PROFILE** Supplier T<sub>p</sub> ≥ T<sub>c</sub> User $T_p \le T_c$ T<sub>c</sub> -5°C Tp Temperature 📑 T<sub>c</sub> -5°C Max. Ramp Up Rate = 3°C/s Max. Ramp Down Rate = 6°C/s $T_L$ T<sub>smax</sub> Preheat Area T<sub>smin</sub> 25 Time 25°C to Peak IPC-020d-5-1

Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150°C
Temperature Max. (Tsmax)	150	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



- One time soldering is recommended for all soldering method.
- Do not solder more than three times for IR reflow soldering.

#### **DISCLAIMER**

- JIEJIE is continually improving the quality, reliability, function and design. JIEJIE reserves the right to make changes without further notices.
- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
- JIEJIE makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, JIEJIE disclaims (a) any and all liability arising out of the application or use of any product, (b) any and all liability, including without limitation special, consequential or incidental damages, and (c) any and all implied warranties, including warranties of fitness for particular
- The products shown in this publication are designed for the general use in electronic applications such as office automation, equipment, communications devices, audio/visual equipment, electrical application and instrumentation purpose, non-infringement and merchantability.
- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact JIEJIE sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary
  over time. All operating parameters, including typical parameters, must be validated in each
  customer application by the customer's technical experts. Product specifications do not expand or
  otherwise modify JIEJIE's terms and conditions of purchase, including but not limited to the warranty
  expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.